

1200V, 50A, N-channel SiC power MOSFET

General Description:

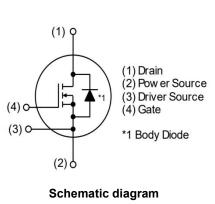
NCES120R036T4 is a SiC MOSFET that contributes to miniaturization and low power consumption of applications. This product achieves industry-leading low on-resistance without sacrificing short-circuit withstand time. This is a 4-pin package type with a driver source terminal that can maximize the high-speed switching performance that is a feature of SiC MOSFETs.

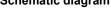
Features

- Low on-resistance
- Fast switching speed
- Fast reverse recovery
- Easy to parallel
- Simple to drive
- Pb-free lead plating; RoHS compliant

Application

- Solar inverters
- DC/DC converters
- Switch mode power supplies
- Induction heating
- Motor drives







TO-247-4L

Package Marking and Ordering Information

Device	Device Package	Device Marking
NCES120R036T4	TO-247-4L	NCES120R036T4

Absolute Maximum Ratings (T_C=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	1200	V
Gate-Source Voltage	Vgs	-4 to +21	V
Drain Current-Continuous (Note 1)	I _D	50	А
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	40	Α
Pulsed Drain Current (Note 1)	I _{DM}	125	Α
Maximum Power Dissipation	P _D	235	W
Recommended turn-on gate - source drive voltage	V _G S_on	+15 to +18	V
Recommended turn-off gate - source drive voltage	V _{GS_off}	0	V
Virtual junction temperature	T _{vj}	175	$^{\circ}$
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-40 To 175	°C



NCES120R036T4

Thermal Characteristic

Symbol	Dovomatav		Units		
Symbol	Parameter	Min	Тур	Max	Units
R _{θJC}	Thermal Resistance, Junction to case		0.45	0.64	°C/W

Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics				•		
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =5.3mA	1200	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =1200V,V _{GS} =0V	-	1	-	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =-4V / +21V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	·			•		
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =10V,I _D =11.1mA	2.8	4	4.8	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =18V, I _D =25A	-	36	45	mΩ
Gate input resistance	R _G	f=1MHZ, open drain	-	2	-	Ω
Forward Transconductance	g FS	V _{DS} =10V, I _D =25A		8		S
Dynamic Characteristics (Note 4)	·					
Input Capacitance	Clss	\/ 000\/\/ 0\/	-	2520	-	pF
Output Capacitance	Coss	V_{DS} =800V, V_{GS} =0V, f =1MHz	-	74	-	pF
Reverse Transfer Capacitance	C _{rss}	I – IIVIMZ	-	4	-	pF
Switching Characteristics (Note 4)	·					
Turn-on Delay Time	t _{d(on)}		-	8.1	-	ns
Turn-on Rise Time	t _r	V _{DD} =800V,I _D =25A V _{GS} =+18V	-	15	-	ns
Turn-Off Delay Time	t _{d(off)}	/ 0V,R _G =3.3Ω,L=250μH	-	29	-	ns
Turn-Off Fall Time	t _f		-	9.6	-	ns
Total Gate Charge	Qg	\/ -000\/ L -05A	-	92	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =800V,I _D =25A,	-	24	-	nC
Gate-Drain Charge	Q_{gd}	- V _{GS} =18V		28	-	nC
Drain-Source Diode Characteristics				•		
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _D =25A	-	3.5	-	V
Reverse Recovery Time	t _{rr}	T 0500 L 054 V 000V	-	9.2		ns
Reverse Recovery Charge	Qrr	$T_J = 25^{\circ}C$, $I_F = 25A$, $V_R = 800V$,	-	140		nC
Peak reverse recovery current	I _{rrm}	di/dt = 3700A/µs ^(Note3)		31		Α

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. PW \leq 10 μ s, Duty cycle \leq 1%
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production



Test Circuit

Fig.1-1 Gate Charge Measurement Circuit

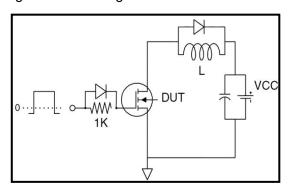


Fig.1-2 Gate Charge Waveform

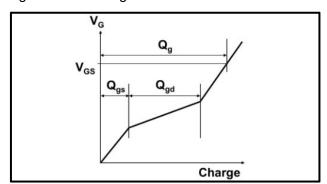
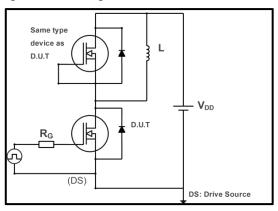
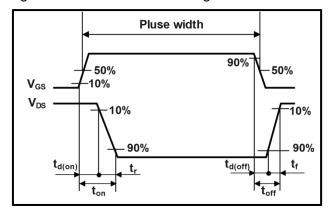


Fig.2-1 Switching Characteristics Measurement Circuit Fig.2-2 Waveforms for Switching Time







Typical Electrical and Thermal Characteristics

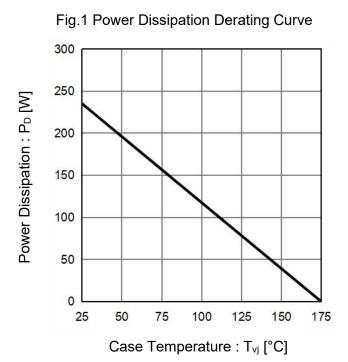


Fig.2 Maximum Safe Operating Area 1000 Operation in this area is limited by R_{DS(on)} Drain Current : I_D [A] 100 10 PW = 10µs* PW = 100µs PW = 1ms 1 PW = 10ms T_c = 25°C Single Pulse Calculation(PW≤10µs) 0.1 0.1 1 10 100 1000 10000 Drain - Source Voltage : V_{DS} [V]

Fig.3 Typical Transient Thermal Impedance vs. Pulse Width

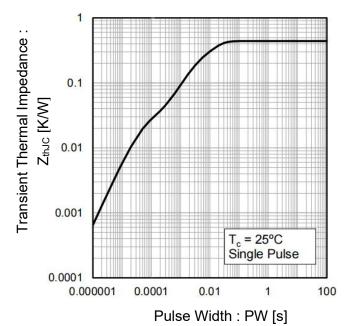




Fig.4 T_{vj} = 25° C Typical Output Characteristics

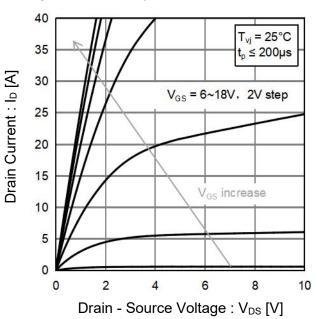


Fig.5 T_{vj} = 25°C 3rd Quadrant Characteristics

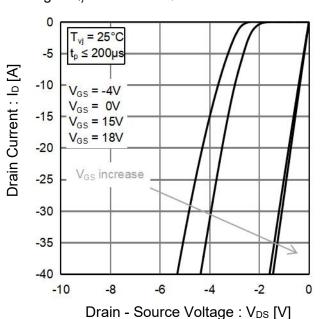


Fig.6 T_{vj} = 150° C Typical Output Characteristics

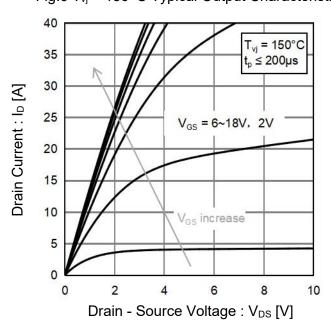


Fig.7 T_{vj} = 150°C 3rd Quadrant Characteristics

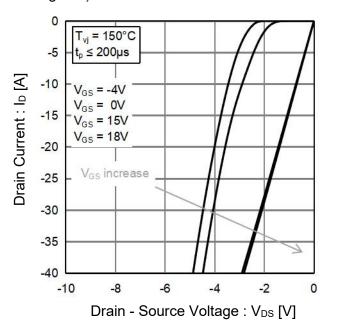




Fig.8 Typical Transfer Characteristics

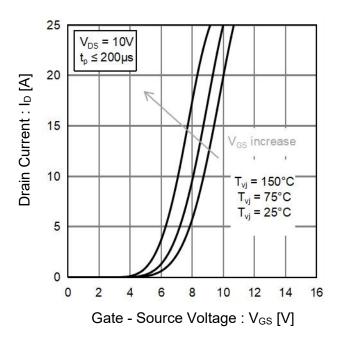


Fig.9 Body Diode Forward Voltage vs. Gate - Source Voltage

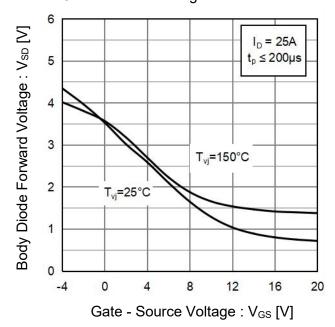


Fig.10 Gate Threshold Voltage vs. Virtual Junction Temperature

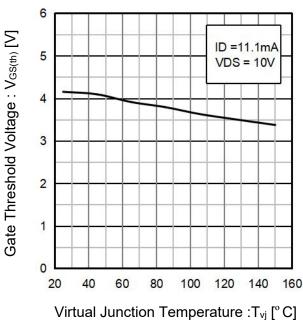


Fig.11 Static Drain - Source On - State Resistance vs. Gate - Source Voltage

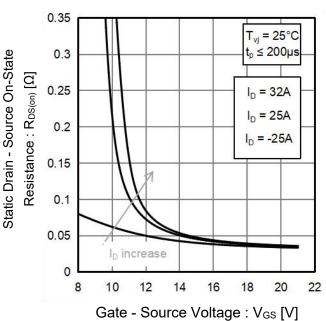




Fig.12 Static Drain - Source On - State Resistance vs. Virtual Junction Temperature

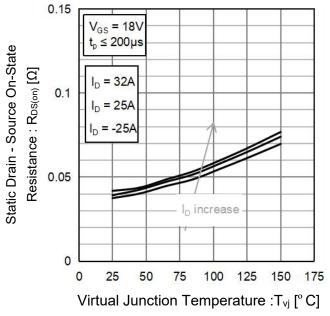


Fig.13 Static Drain - Source On - State Resistance vs. Drain Current

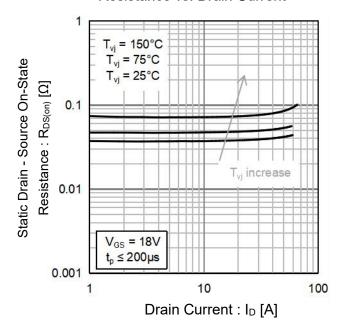


Fig.14 Typical Capacitance vs. Drain - Source Voltage

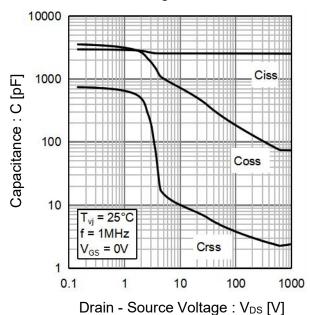
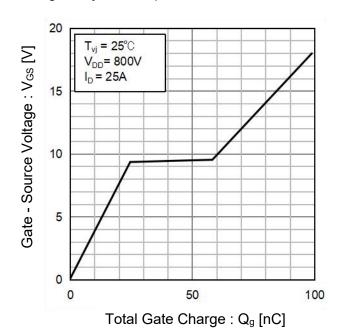
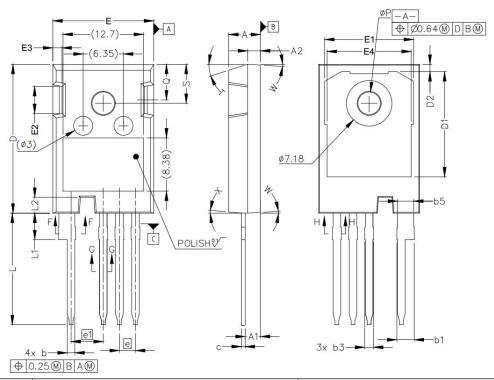


Fig.15 Dynamic Input Characteristics





TO-247-4L Package Information



0	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	4.83	5.21	0.19	0.21	
A1	2.29	2.54	0.09	0.10	
A2	1.91	2.16	0.08	0.09	
b1	2.39	2.94	0.09	0.12	
b3	1.07	1.60	0.04	0.06	
b5	2.39	2.69	0.09	0.11	
С	0.55	0.68	0.02	0.03	
D	23.30	23.60	0.92	0.93	
D1	16.25	17.65	0.64	0.69	
D2	0.95	1.25	0.04	0.05	
E	15.75	16.13	0.62	0.64	
E1	13.10	14.15	0.52	0.56	
E2	3.68	5.10	0.14	0.20	
E3	1.00	1.90	0.04	0.07	
E4	12.38	13.43	0.49	0.53	
е	2.54 E	2.54 BSC		BSC	
e1	5.08 E	BSC	0.2 E	BSC	
L	17.31	17.82	0.68	0.70	
L1	3.97	4.37	0.16	0.17	
L2	2.35	2.65	0.09	0.10	
ФР	3.51	3.65	0.14	0.14	
Q	5.49	6.00	0.22	0.24	
S	6.04	6.30	0.24	0.25	
Т	17.5° I	7.5° REF. 0.69° REF.		REF.	
W	3.5° REF.		0.14°	REF.	
X	4.0° F	REF.	0.16°	REF.	





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